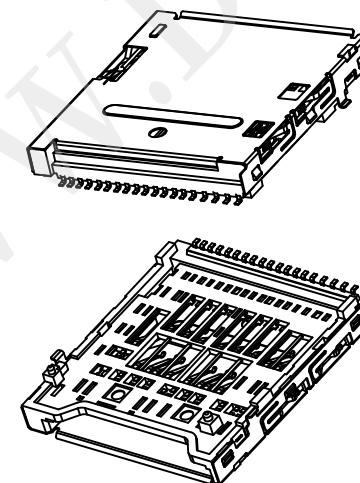
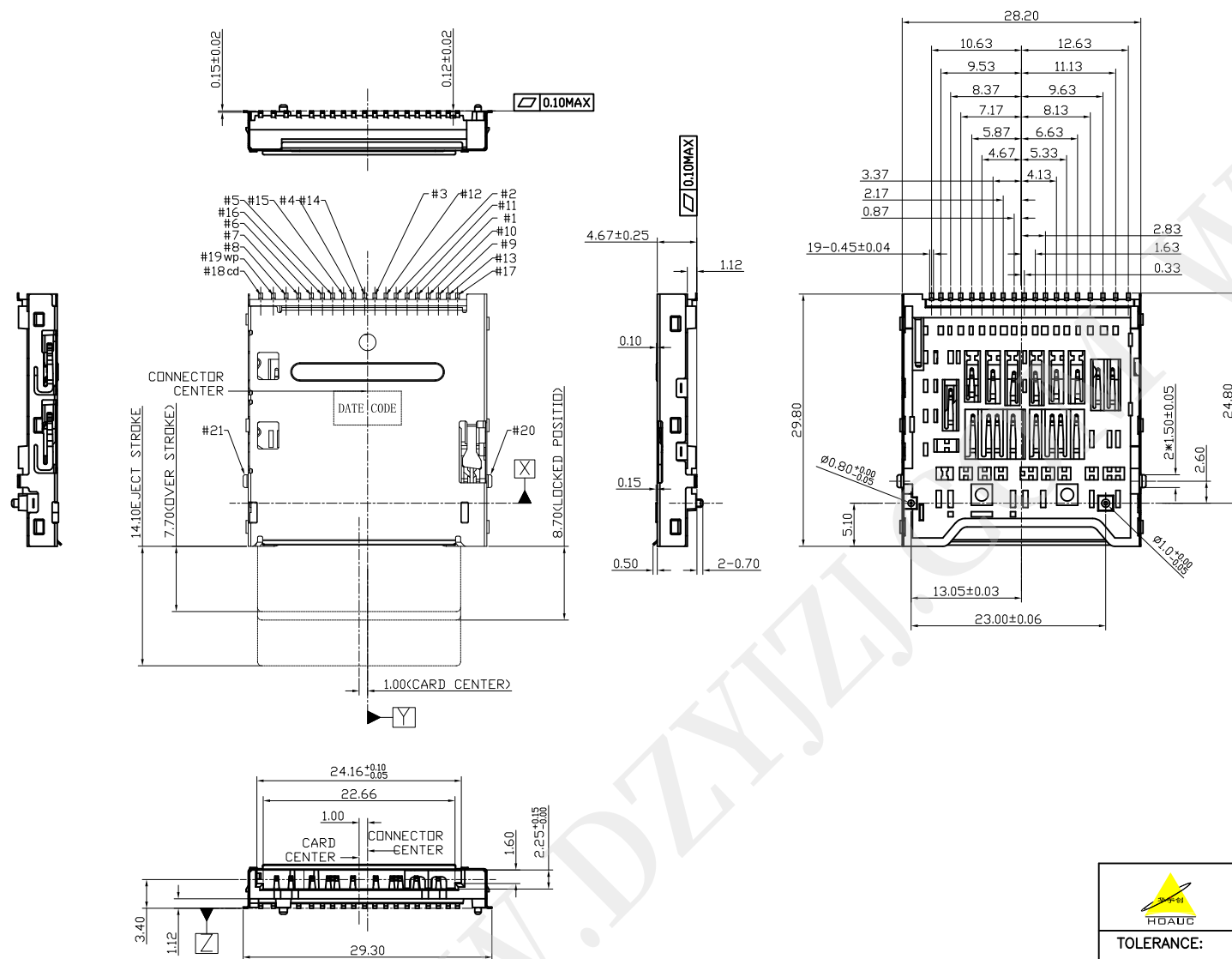




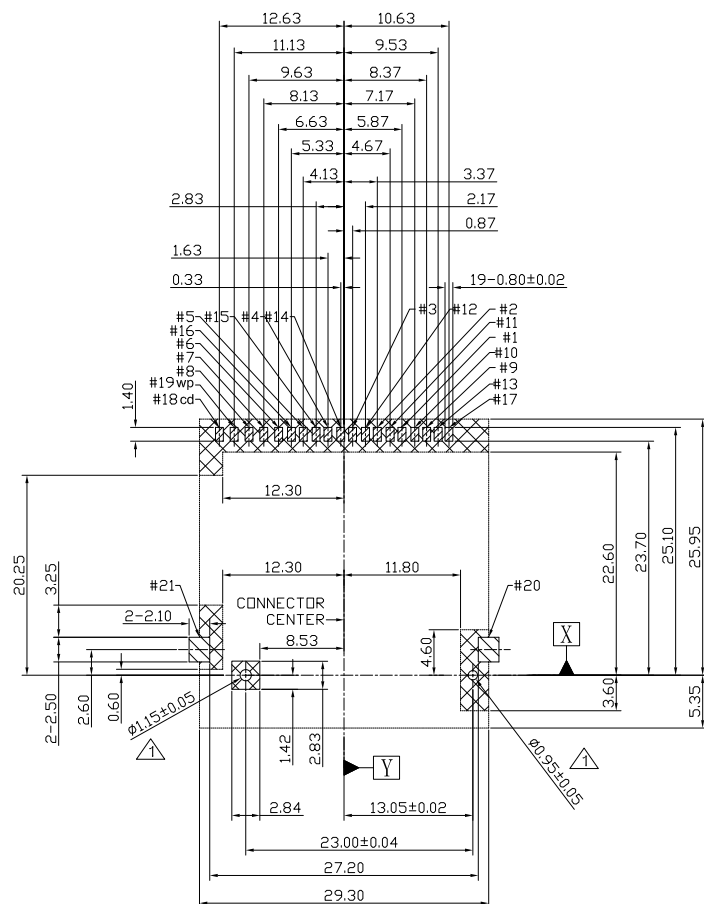
注解:

1. 材料:
 - 1-1 主体: LCP E471I+30%玻纤, UL94V-0, 黑色, 符合泰硕HF要求
 - 1-2 端子: C5210-EH 料厚=0.12±0.02
 - 1-3 铁壳: SUS301-3/4H 料厚=0.15±0.02
2. 电镀:
 - 2-1 端子:
 - 2-1-1 接触面积: 接触点镀金1U"以上, 镍底50U"以上。
 - 2-1-2 焊锡面积: 镀锡80U"以上, 镍底50U"以上。
 - 2-2 铁壳:
 - 2-2-1 焊界面镀金1U"以上, 所有面积镍底镀50U"以上。
3. 焊锡面共面度最大0.1mm
4. 物料必须满足泰硕HF WD-3-I-091规范要求
- 5-1. 工作温度: -30° C到+85° C.
- 5-2. 储存温度: -40° C到+85° C.



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"				SD PUSH 4.0板上型 4.67H 垫高1.	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC109-SD19-467
		马跃	2014-02-23	MOLD NO.	
SCALE:1:1 SIZE: A4		APPROVED BY:	DATE :	DRAW NO:	HYC-2510151138
		邱敏	2014-02-23	SHEET NO.	1 OF 1



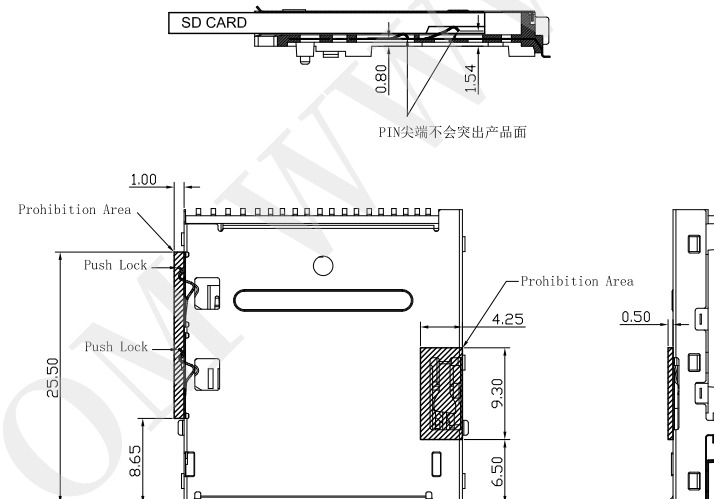
RECOMMEND P.C. BOARD LAYOUT (TOP VIEW)
TOLERANCE UNLESS OTHERWISE SPEC ± 0.05

NOTES:

	PAD AREA
	NO PARTS AREA
	KEEP OUT AREA
	GND ONLY

NO.	SD NAME	USH-LL NAME
1	CD/DAT3	
2	CMD	
3	VSS1	VSS1
4	VDD	VDD1
5	CLK	
6	VSS2	VSS2
7	DAT0	RCLK+
8	DAT1	RCLK-
9	DAT2	
10		VSS3
11		DO+
12		DO-
13		VSS4
14		VDD2
15		D1-
16		D1+
17		VSS5
18	CD SW	
19	WP SW	
20	GND SW	
21	GND SW	

模拟示意图供参考



	W/P CONTACT		C/D CONTACT
	WRITE PROTECT POSITION	WRITE ENABLE POSITION	
CARD UNINSERTION	CLOSE	CLOSE	CLOSE
CARD HALF INSERTION	OPEN	OPEN	CLOSE
CARD INSERTION	CLOSE	OPEN	OPEN



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X" ± 2 " X.X" ± 0.5 "	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: SD PUSH 4.0板上型 4.67H 垫高1.1
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC109-SD19-467
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2510151138
			SHEET NO. 1 OF 1